



Enterprises, Inc.

High-Technology Equipment Specialists

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Logitech 1WBS2 Wafer Substrate Bonding System



- Temporary Wax Mounting Bonder for Lapping and Polishing
- 100 mm Max Substrate Size
- Manufactured 2001

TERMS:

COD

DELIVERY: 2 Weeks ARO, 50% Deposit w/ Order

FOB Belmont, California

SUBJECT TO PRIOR SALE

CONDITION: Can Demo at our facility